

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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#### 8.89mmx8.89mm LED LIGHT BAR

Part Number: KB2855CGKD

Green

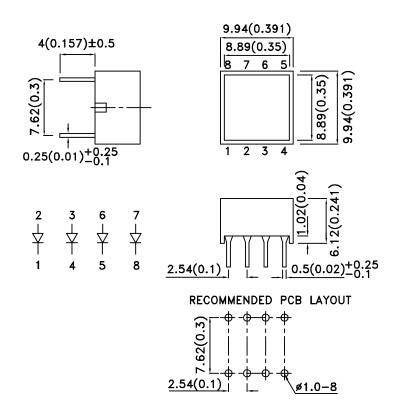
#### **Features**

- Uniform light emitting area.
- Easily mounted on P.C. boards.
- Flush mountable.
- Excellent on/off contrast.
- Can be used with panels and legend mounts.
- RoHS compliant.

### **Description**

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

### **Package Dimensions& Internal Circuit Diagram**





1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01")unless otherwise noted.

2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

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 APPROVED: WYNEC
 CHECKED: Joe Lee
 DRAWN: D.N.Huang
 ERP: 1334000643

### **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [1] @ 20mA	
			Min.	Тур.
KB2855CGKD	Green (AlGaInP)	Green Diffused	80	140
REZUGUUND	order ( would )	Green Billacea	*20	*48

### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	570		nm	I=20mA
Δλ1/2	Spectral Line Half-width	Green	20		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.1	2.5	V	IF=20mA
lR	Reverse Current	Green		10	uA	V <sub>R</sub> =5V

### Notes:

- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

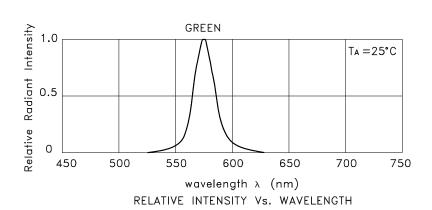
### Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating / Storage Temperature	-40°C To +85°C		
Lead Solder Temperature[2]	260°C For 3-5 Seconds		

- Notes: 1. 1/10 Duty Cycle, 0.1ms Pulse Width. 2. 2mm below package base.

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Notes:
1. Luminous intensity/ luminous Flux: +/-15%.
\*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.



### Green KB2855CGKD

50

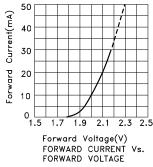
40

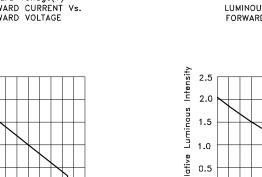
30 20

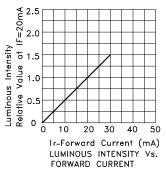
10

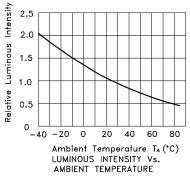
0 20 40 60

Forward Current(mA)





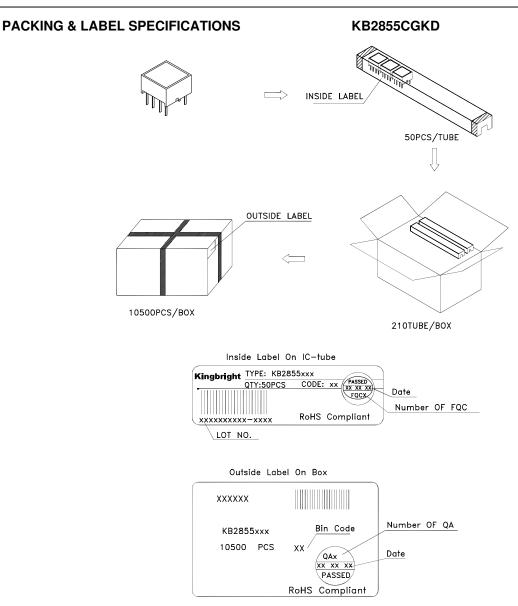




80 100

Ambient Temperature TA(°C)

FORWARD CURRENT DERATING CURVE



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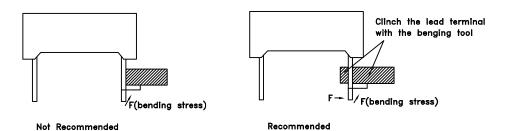
- 1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
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### THROUGH HOLE DISPLAY MOUNTING METHOD

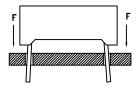
### Lead Forming

Do not bend the component leads by hand without proper tools. The leads should be bent by clinching the upper part of the lead firmly such that the bending force is not exerted on the plastic body.

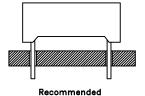


### Installation

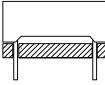
- 1. The installation process should not apply stress to the lead terminals.
- 2. When inserting for assembly, ensure the terminal pitch matches the substrate board's hole pitch to prevent spreading or pinching the lead terminals.



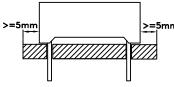




3. The component shall be placed at least 5mm from edge of PCB to avoid damage caused excessive heat during wave soldering.



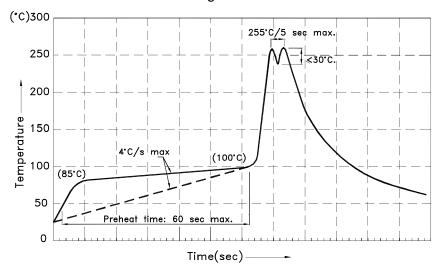




Recommended

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### Recommended Wave Soldering Profiles:



#### Notes:

- 1.Recommend pre—heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of 260°C
- 2.Peak wave soldering temperature between 245°C  $\sim$  255°C for 3 sec (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above 85°C.
- 4. Fixtures should not incur stress on the component when mounting and during soldering proc $5.SAC\ 305\ solder$  alloy is recommended.
- 6.No more than one wave soldering pass.

### Soldering General Notes:

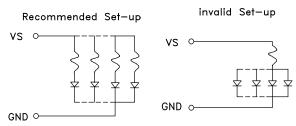
- 1. Through—hole displays are incompatible with reflow soldering.
- 2. If components will undergo multiple soldering processes, or other processes where the components may be subjected to intense heat, please check with Kingbright for compatibility.

### **CLEANING**

- 1.Mild "no-clean" fluxes are recommended for use in soldering.
- If cleaning is required, Kingbright recommends to wash components with water only. Do not use harsh organic solvents for cleaning, because they may damage the plastic parts .And the devices should not be washed for more than one minute.

### CIRCUIT DESIGN NOTES

- 1.Protective current—limiting resistors may be necessary to operate the Displays.
- 2.LEDs mounted in parallel should each be placed in series with its own current—limiting resistor.



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